



N-Channel 12-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
	0.0053 at V _{GS} = 4.5 V	21.5				
12	0.006 at V _{GS} = 2.5 V	20.2	29.5 nC			
	0.0074 at V _{GS} = 1.8 V	18.2				

SO-8 S 1 8 D S 2 7 D S 3 6 D G 4 5 D

Ordering Information: Si4866BDY-T1-E3 (Lead (Pb)-free)

Si4866BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

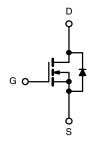
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Synchronous Rectifier
- Point-of-Load Synchronous Buck Converter



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	12	V		
Gate-Source Voltage	V _{GS}	± 8			
	T _C = 25 °C		21.5		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	1-	17.2		
Continuous Diam Current (1) = 150 C)	T _A = 25 °C	I _D	16.1 ^{b,c}		
	T _A = 70 °C		12.9 ^{b,c}		
Pulsed Drain Current	I _{DM}	50	A		
Continuous Course Drain Diada Current	T _C = 25 °C	I.	4.0		
Continuous Source-Drain Diode Current	T _A = 25 °C	ls —	2.3 ^{b,c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20		
Avalanche Energy	L = 0.1 IIII	E _{AS}	20	mJ	
	T _C = 25 °C		4.45		
Maximum Dawar Dissination	T _C = 70 °C	P _D	2.85	w	
Maximum Power Dissipation	T _A = 25 °C	r _D	2.50 ^{b,c}	vv	
	T _A = 70 °C		1.6 ^{b,c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b,d}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	23	28	C/ VV	

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 90 °C/W.

Si4866BDY

Vishay Siliconix



SPECIFICATIONS $T_J = 25 ^{\circ}C$, Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	Symbol	rest conditions	IVIIII.	тур.	IVIAA.	Oilit	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	12			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{.1}$	- GS - 1, 1D 1 p. 1		12		•	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 3.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	0.4	- 0.0	1.0	V	
	_	$V_{DS} = V_{GS}, V_{DS} = \pm 8 \text{ V}$	0.4			-	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$	1			μΑ	
	1		00		10	Δ.	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α	
_	_	$V_{GS} = 4.5 \text{ V}, I_D = 12 \text{ A}$		0.0042			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 10 \text{ A}$		0.0048	0.0060		
		$V_{GS} = 1.8 \text{ V}, I_D = 8 \text{ A}$		0.006	0.0074		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 12 A		80		S	
Dynamic ^b							
Input Capacitance	C _{iss}			5020		pF	
Output Capacitance	C _{oss}	$V_{DS} = 6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1305			
Reverse Transfer Capacitance	C _{rss}			805			
	Qg	$V_{DS} = 6 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		52	80	nC	
Total Gate Charge				29.5	45		
Gate-Source Charge	Q_{gs}	$V_{DS} = 6 \text{ V}, V_{GS} = 2.5 \text{ V}, I_{D} = 10 \text{ A}$		6.2			
Gate-Drain Charge	Q_{gd}			8.9			
Gate Resistance	R_{g}	f = 1 MHz		0.8	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			26	40		
Rise Time	t _r	$V_{DD} = 6 \text{ V}, R_1 = 1.2 \Omega$		18	30		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		85	130		
Fall Time	t _f			32	50		
Turn-On Delay Time	t _{d(on)}			13	25	ns	
Rise Time	t _r	$V_{DD} = 6 \text{ V}, R_1 = 1.2 \Omega$		12	24	•	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		57	90		
Fall Time	t _f	Ĭ		9	18	1	
Drain-Source Body Diode Characteristi	T.					I	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			4		
Pulse Diode Forward Current ^a	I _{SM}	-			50	A	
Body Diode Voltage	V _{SD}	I _S = 2.3 A		0.62	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}	<u> </u>		50	80	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			35	55	nC	
Reverse Recovery Fall Time	t _a			19	- 55		
Reverse Recovery Rise Time	t _b			31		ns	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

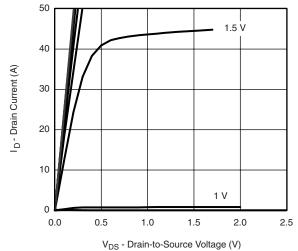
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

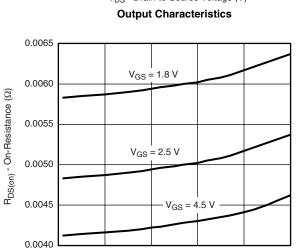
b. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



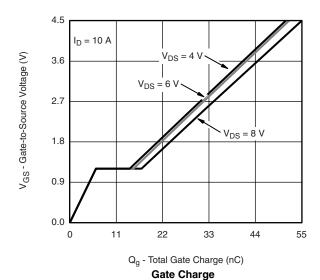


20

I_D - Drain Current (A) On-Resistance vs. Drain Current and Gate Voltage

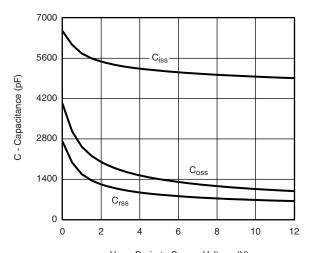
40

50

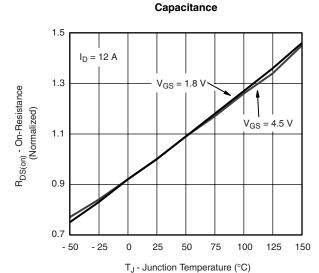


2.0 1.6 I_D - Drain Current (A) 25 °C 1.2 0.8 T_C = 125 °C 0.4 - 55 °C 0.0 0.0 0.3 0.6 0.9 1.2 1.5

V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



V_{DS} - Drain-to-Source Voltage (V)



On-Resistance vs. Junction Temperature

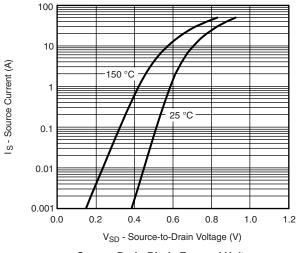
0

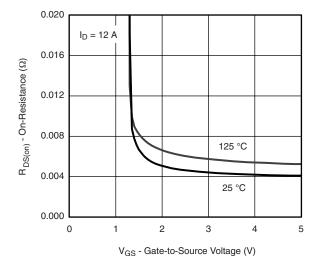
10

Vishay Siliconix

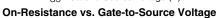
VISHAY.

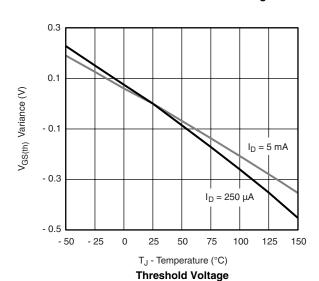
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

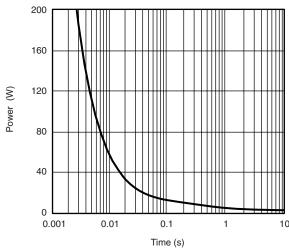




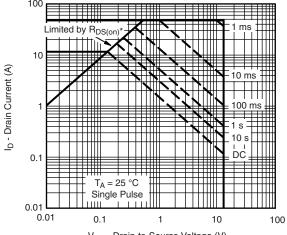
Source-Drain Diode Forward Voltage







Single Pulse Power, Junction-to-Ambient

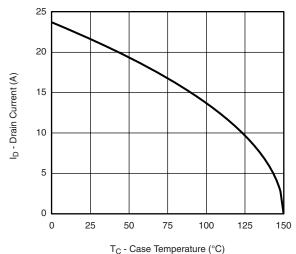


 $V_{DS} \text{ - Drain-to-Source Voltage (V)} \\ ^*V_{GS} > \text{minimum V}_{GS} \text{ at which R}_{DS(on)} \text{ is specified}$

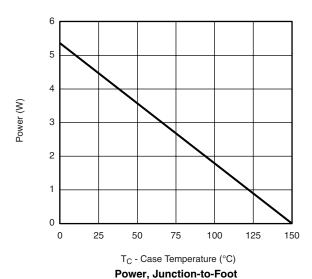
Safe Operating Area, Junction-to-Ambient

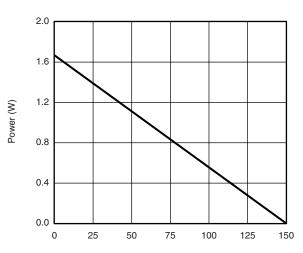


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





T_A - Ambient Temperature (°C)

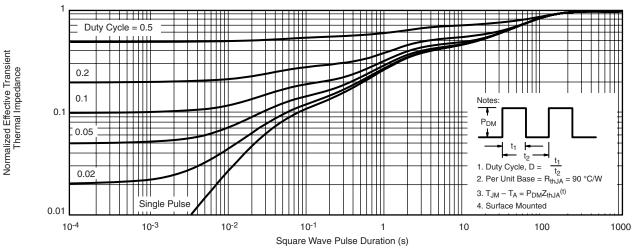
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

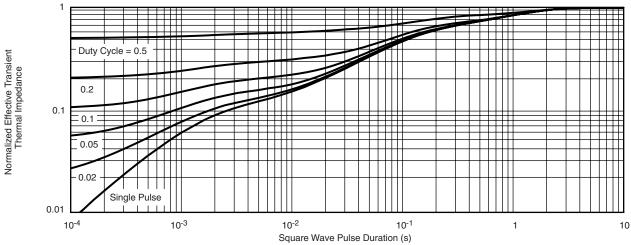
Vishay Siliconix



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?70341.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







MILLIMETERS			INC	ICHES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

Ш



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.